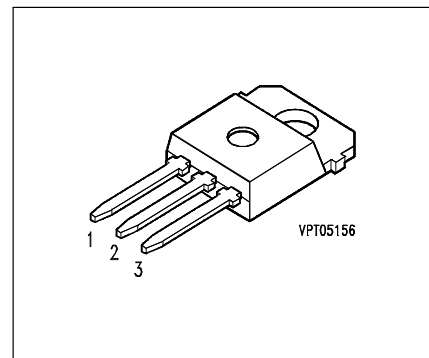


### SIPMOS<sup>®</sup> Power Transistor

- N channel
- Enhancement mode
- Avalanche-rated



Pin 1	Pin 2	Pin 3
G	D	S

Type	V <sub>DS</sub>	I <sub>D</sub>	R <sub>DS(on)</sub>	Package	Ordering Code
BUZ 323	400 V	15 A	0.3 Ω	TO-218 AA	C67078-S3127-A2

#### Maximum Ratings

Parameter	Symbol	Values	Unit
Continuous drain current <i>T<sub>C</sub></i> = 25 °C	<i>I<sub>D</sub></i>	15	A
Pulsed drain current <i>T<sub>C</sub></i> = 25 °C	<i>I<sub>Dpuls</sub></i>	60	
Avalanche current, limited by <i>T<sub>jmax</sub></i>	<i>I<sub>AR</sub></i>	15	
Avalanche energy, periodic limited by <i>T<sub>jmax</sub></i>	<i>E<sub>AR</sub></i>	18	mJ
Avalanche energy, single pulse <i>I<sub>D</sub></i> = 15 A, <i>V<sub>DD</sub></i> = 50 V, <i>R<sub>GS</sub></i> = 25 Ω <i>L</i> = 6.14 mH, <i>T<sub>j</sub></i> = 25 °C	<i>E<sub>AS</sub></i>	790	
Gate source voltage	<i>V<sub>GS</sub></i>	± 20	V
Power dissipation <i>T<sub>C</sub></i> = 25 °C	<i>P<sub>tot</sub></i>	170	W
Operating temperature	<i>T<sub>j</sub></i>	-55 ... + 150	°C
Storage temperature	<i>T<sub>stg</sub></i>	-55 ... + 150	
Thermal resistance, chip case	<i>R<sub>thJC</sub></i>	≤ 0.74	K/W
Thermal resistance, chip to ambient	<i>R<sub>thJA</sub></i>	75	
DIN humidity category, DIN 40 040		E	
IEC climatic category, DIN IEC 68-1		55 / 150 / 56	

**Electrical Characteristics, at  $T_j = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Static Characteristics</b>					
Drain- source breakdown voltage $V_{GS} = 0\text{ V}, I_D = 0.25\text{ mA}, T_j = 25\text{ }^\circ\text{C}$	$V_{(BR)DSS}$	400	-	-	V
Gate threshold voltage $V_{GS}=V_{DS}, I_D = 1\text{ mA}$	$V_{GS(th)}$	2.1	3	4	
Zero gate voltage drain current $V_{DS} = 400\text{ V}, V_{GS} = 0\text{ V}, T_j = 25\text{ }^\circ\text{C}$ $V_{DS} = 400\text{ V}, V_{GS} = 0\text{ V}, T_j = 125\text{ }^\circ\text{C}$	$I_{DSS}$	-	0.1 10	1 100	$\mu\text{A}$
Gate-source leakage current $V_{GS} = 20\text{ V}, V_{DS} = 0\text{ V}$	$I_{GSS}$	-	10	100	nA
Drain-Source on-resistance $V_{GS} = 10\text{ V}, I_D = 9.5\text{ A}$	$R_{DS(on)}$	-	0.25	0.3	$\Omega$

**Electrical Characteristics**, at  $T_j = 25^\circ\text{C}$ , unless otherwise specified

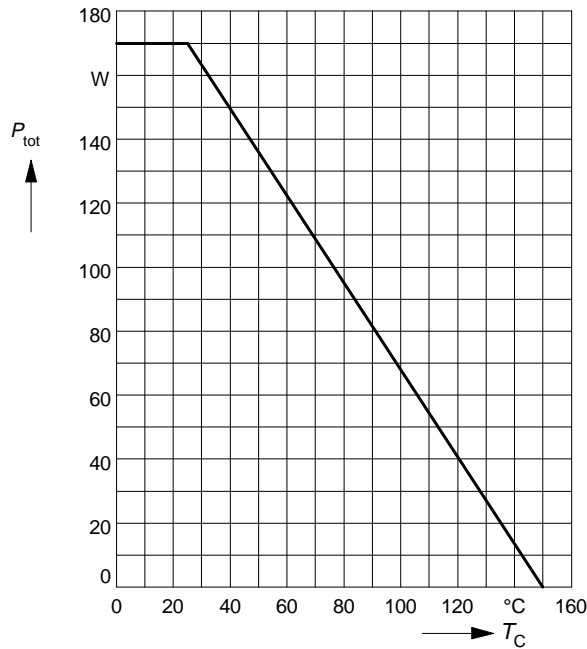
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Dynamic Characteristics</b>					
Transconductance $V_{DS} \geq 2 * I_D * R_{DS(on)max}$ , $I_D = 9.5 \text{ A}$	$g_{fs}$	8	14.5	-	S
Input capacitance $V_{GS} = 0 \text{ V}$ , $V_{DS} = 25 \text{ V}$ , $f = 1 \text{ MHz}$	$C_{iss}$	-	2300	3000	pF
Output capacitance $V_{GS} = 0 \text{ V}$ , $V_{DS} = 25 \text{ V}$ , $f = 1 \text{ MHz}$	$C_{oss}$	-	320	480	
Reverse transfer capacitance $V_{GS} = 0 \text{ V}$ , $V_{DS} = 25 \text{ V}$ , $f = 1 \text{ MHz}$	$C_{rss}$	-	120	180	
Turn-on delay time $V_{DD} = 30 \text{ V}$ , $V_{GS} = 10 \text{ V}$ , $I_D = 2.9 \text{ A}$ $R_{GS} = 50 \Omega$	$t_{d(on)}$	-	40	65	ns
Rise time $V_{DD} = 30 \text{ V}$ , $V_{GS} = 10 \text{ V}$ , $I_D = 2.9 \text{ A}$ $R_{GS} = 50 \Omega$	$t_r$	-	75	115	
Turn-off delay time $V_{DD} = 30 \text{ V}$ , $V_{GS} = 10 \text{ V}$ , $I_D = 2.9 \text{ A}$ $R_{GS} = 50 \Omega$	$t_{d(off)}$	-	270	350	
Fall time $V_{DD} = 30 \text{ V}$ , $V_{GS} = 10 \text{ V}$ , $I_D = 2.9 \text{ A}$ $R_{GS} = 50 \Omega$	$t_f$	-	130	170	

**Electrical Characteristics, at  $T_j = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Reverse Diode</b>					
Inverse diode continuous forward current $T_C = 25^\circ\text{C}$	$I_S$	-	-	15	A
Inverse diode direct current, pulsed $T_C = 25^\circ\text{C}$	$I_{SM}$	-	-	60	
Inverse diode forward voltage $V_{GS} = 0\text{ V}, I_F = 30\text{ A}$	$V_{SD}$	-	1.1	1.5	V
Reverse recovery time $V_R = 100\text{ V}, I_F = I_S, di_F/dt = 100\text{ A}/\mu\text{s}$	$t_{rr}$	-	120	-	ns
Reverse recovery charge $V_R = 100\text{ V}, I_F = I_S, di_F/dt = 100\text{ A}/\mu\text{s}$	$Q_{rr}$	-	0.25	-	$\mu\text{C}$

### Power dissipation

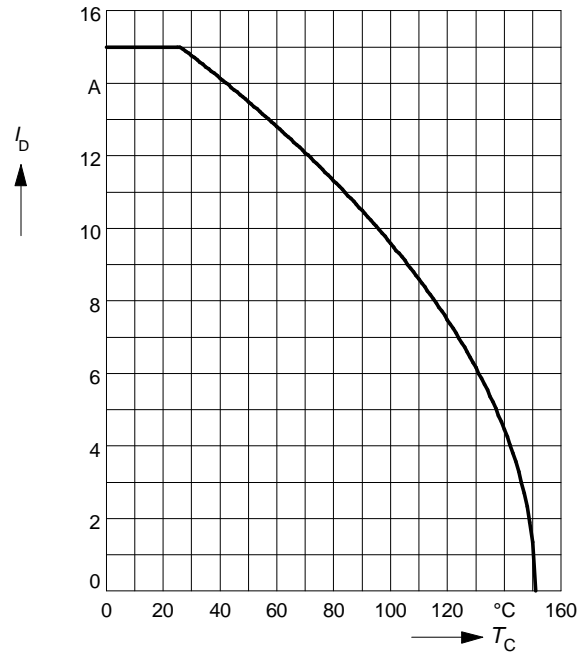
$$P_{\text{tot}} = f(T_C)$$



### Drain current

$$I_D = f(T_C)$$

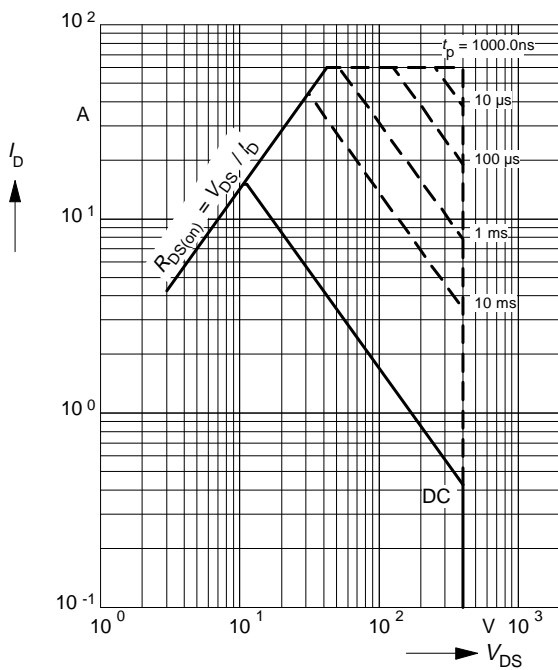
parameter:  $V_{GS} \geq 10 \text{ V}$



### Safe operating area

$$I_D = f(V_{DS})$$

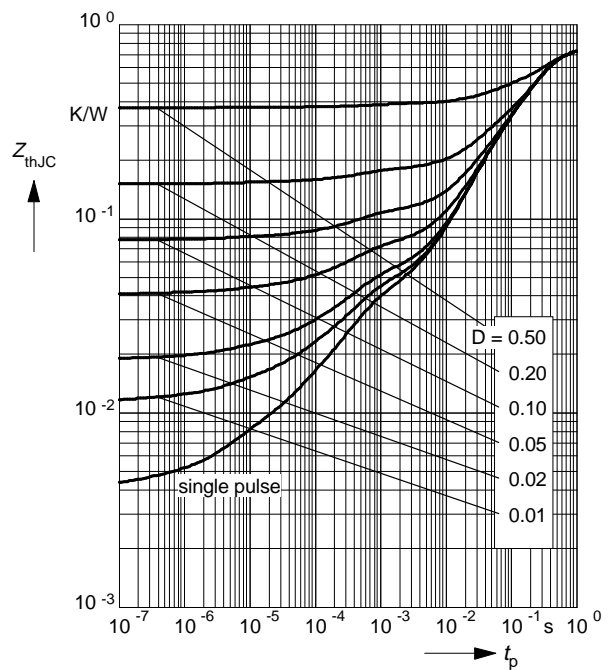
parameter:  $D = 0.01$ ,  $T_C = 25^\circ\text{C}$



### Transient thermal impedance

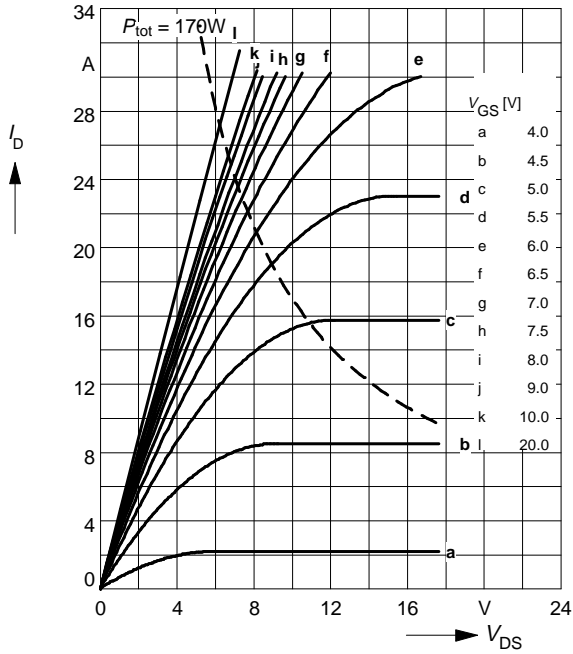
$$Z_{\text{thJC}} = f(t_p)$$

parameter:  $D = t_p / T$



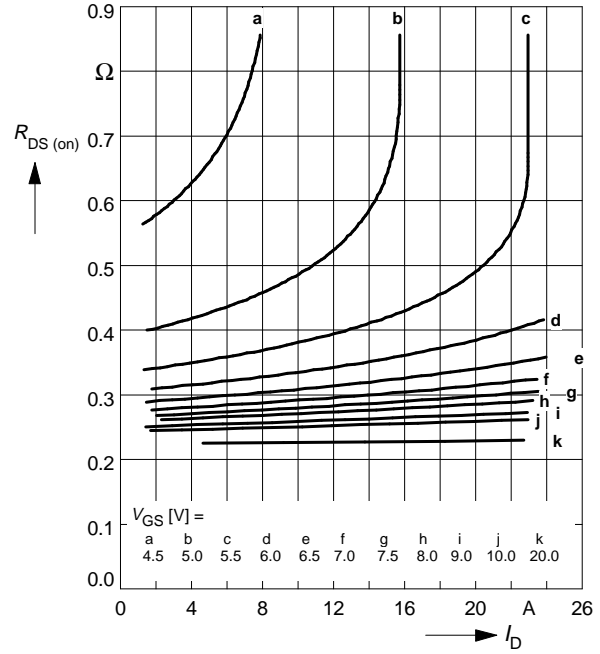
### Typ. output characteristics

$I_D = f(V_{DS})$   
parameter:  $t_p = 80 \mu s$



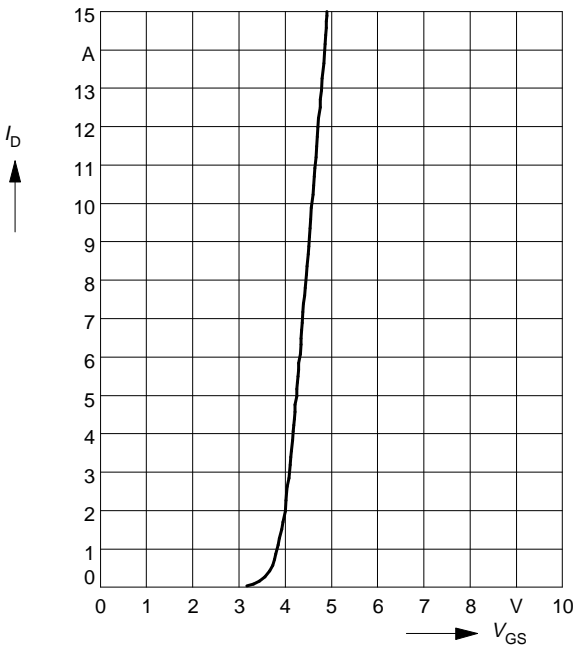
### Typ. drain-source on-resistance

$R_{DS(on)} = f(I_D)$   
parameter:  $V_{GS}$



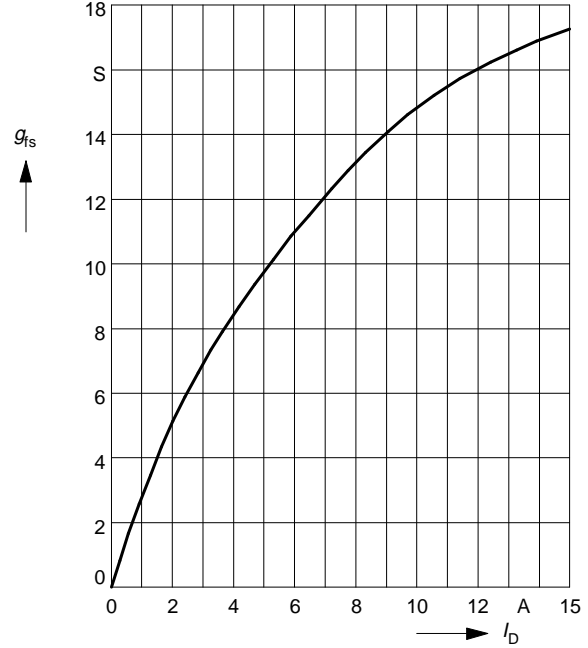
### Typ. transfer characteristics $I_D = f(V_{GS})$

parameter:  $t_p = 80 \mu s$   
 $V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$



### Typ. forward transconductance $g_{fs} = f(I_D)$

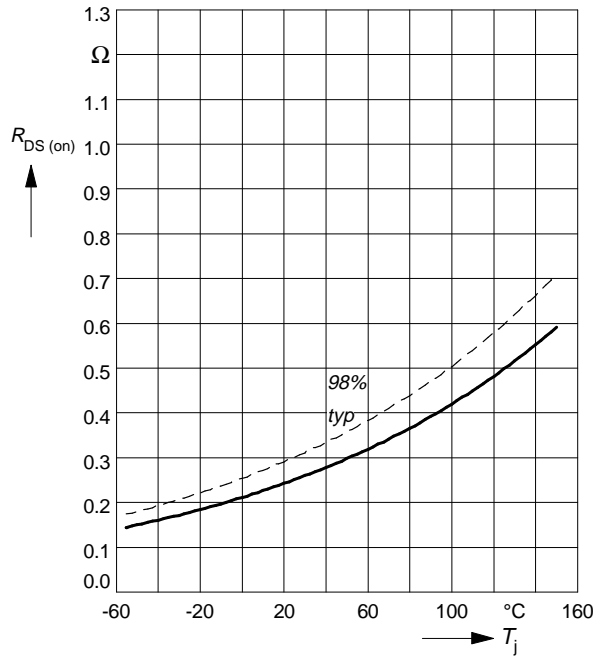
parameter:  $t_p = 80 \mu s$ ,  
 $V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$



### Drain-source on-resistance

$$R_{DS(on)} = f(T_j)$$

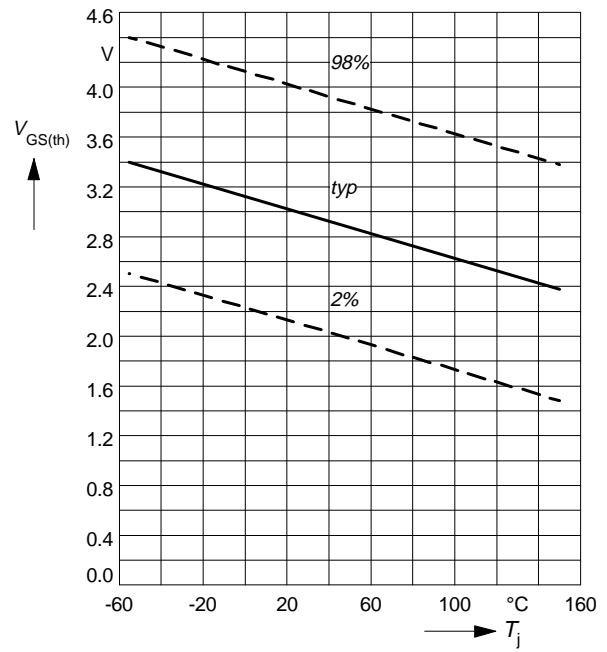
parameter:  $I_D = 9.5 \text{ A}$ ,  $V_{GS} = 10 \text{ V}$



### Gate threshold voltage

$$V_{GS(th)} = f(T_j)$$

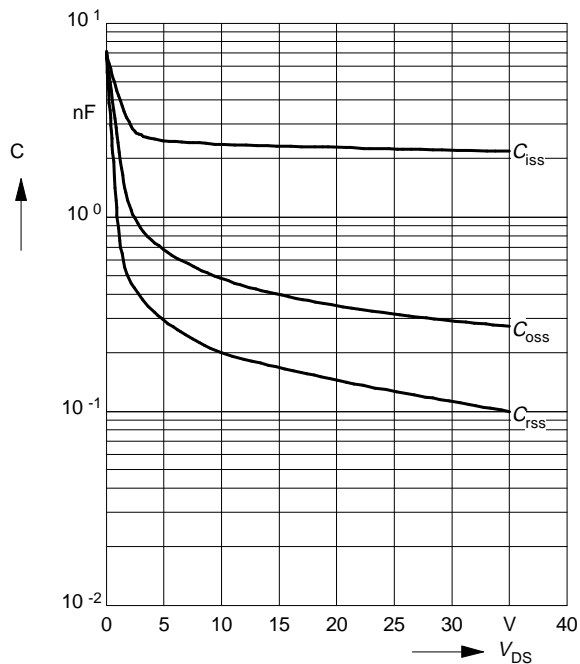
parameter:  $V_{GS} = V_{DS}$ ,  $I_D = 1 \text{ mA}$



### Typ. capacitances

$$C = f(V_{DS})$$

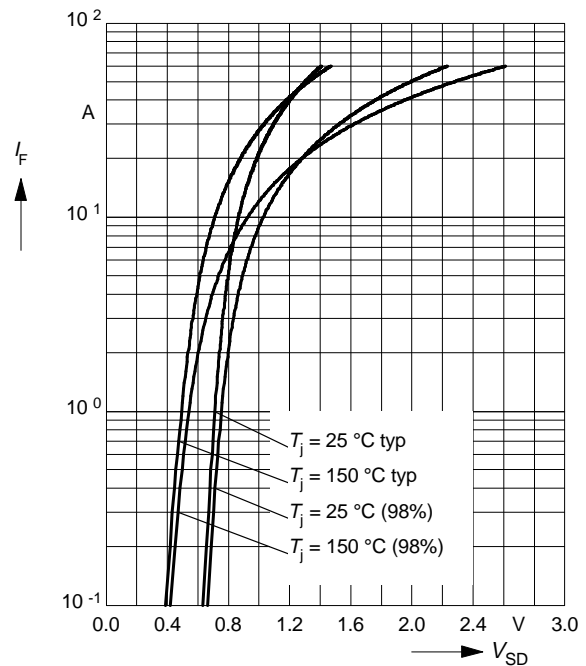
parameter:  $V_{GS} = 0 \text{ V}$ ,  $f = 1 \text{ MHz}$



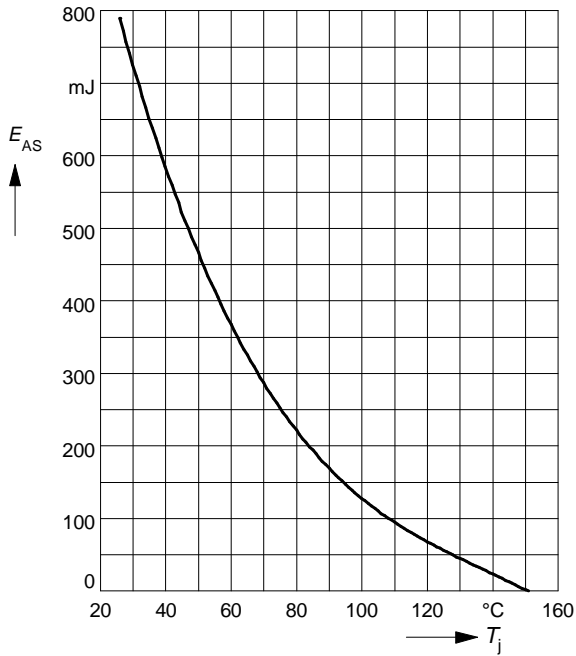
### Forward characteristics of reverse diode

$$I_F = f(V_{SD})$$

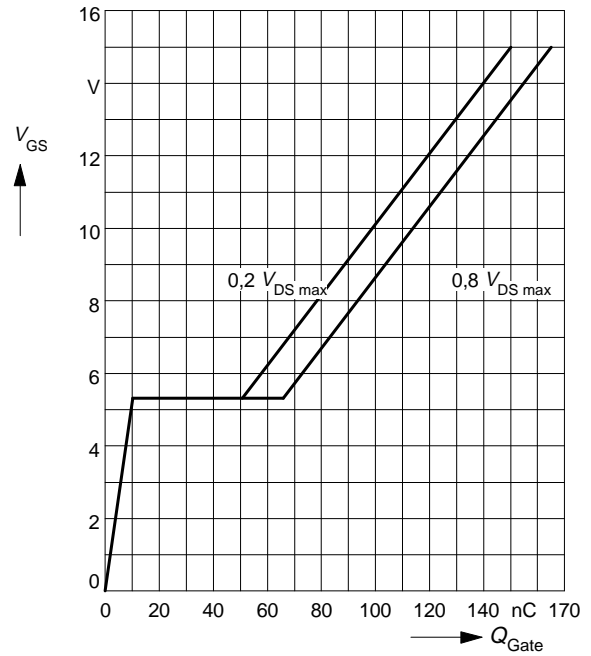
parameter:  $T_j$ ,  $t_p = 80 \mu\text{s}$



**Avalanche energy**  $E_{AS} = f(T_j)$   
 parameter:  $I_D = 15 \text{ A}$ ,  $V_{DD} = 50 \text{ V}$   
 $R_{GS} = 25 \Omega$ ,  $L = 6.14 \text{ mH}$

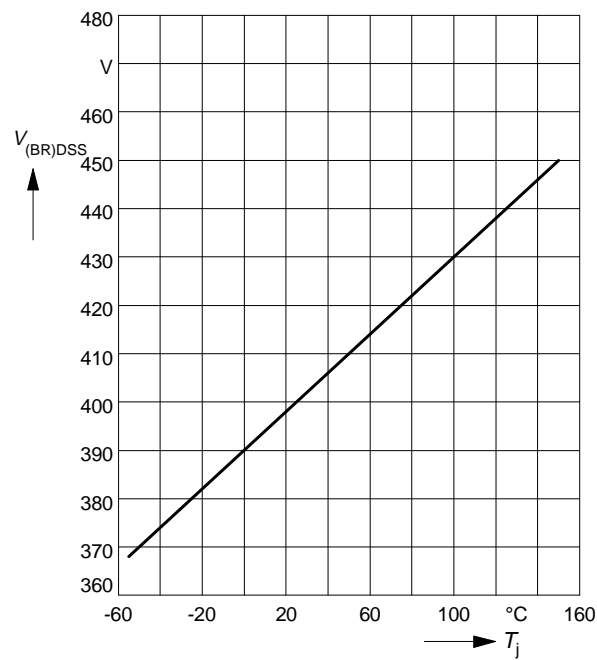


**Typ. gate charge**  
 $V_{GS} = f(Q_{Gate})$   
 parameter:  $I_{D \text{ puls}} = 22 \text{ A}$



**Drain-source breakdown voltage**

$V_{(BR)DSS} = f(T_j)$

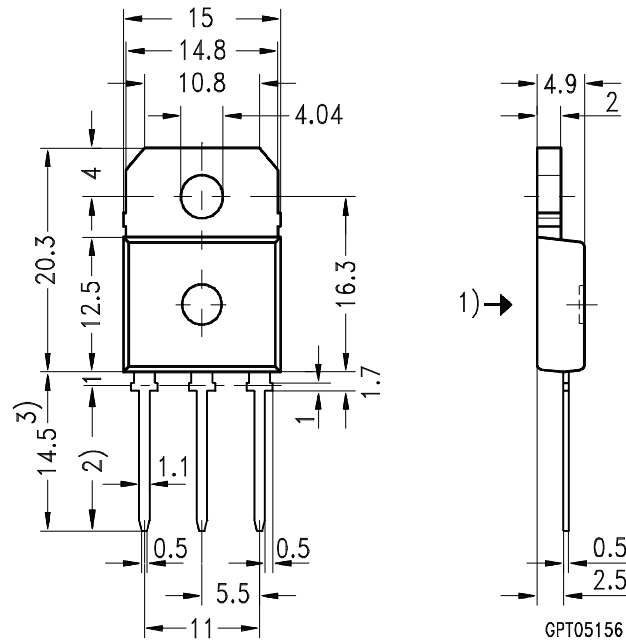




## Package Outlines

TO-218 AA

Dimension in mm



- 1) punch direction, burr max. 0.04
- 2) dip tinning
- 3) max. 15.5 by dip tinning press burr max. 0.05